# The SN54F299 is obsolete and no longer supplied.

## SN54F299, SN74F299 8-BIT UNIVERSAL SHIFT/STORAGE REGISTERS WITH 3-STATE OUTPUTS

SDFS071B - MARCH 1987 - REVISED APRIL 2004

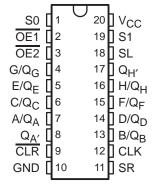
- Four Modes of Operation:
  - Hold (Store)
  - Shift Right
  - Shift Left
  - Load Data
- Operates With Outputs Enabled or at High Impedance
- 3-State Outputs Drive Bus Lines Directly
- Can Be Cascaded for N-Bit Word Lengths
- Direct Overriding Clear
- Applications:
  - Stacked or Pushdown Registers
  - Buffer Storage
  - Accumulator Registers

## description/ordering information

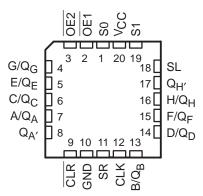
These 8-bit universal shift/storage registers feature multiplexed I/O ports to achieve full 8-bit data handling in a single 20-pin package. Two function-select (S0, S1) inputs and two output-enable (OE1, OE2) inputs can be used to choose the modes of operation listed in the function table.

Synchronous parallel loading is accomplished by taking both S0 and S1 high. This places the 3-state outputs in a high-impedance state and permits data that is applied on the I/O ports to

SN54F299 . . . J PACKAGE SN74F299 . . . DW, N, OR NS PACKAGE (TOP VIEW)



SN54F299 . . . FK PACKAGE (TOP VIEW)



be clocked into the register. Reading out of the register can be accomplished while the outputs are enabled in any mode. Clearing occurs when the clear (CLR) input is low. Taking either OE1 or OE2 high disables the outputs but has no effect on clearing, shifting, or storage of data.

#### **ORDERING INFORMATION**

TA	PACKAG	<sub>SE</sub> †	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 20	SN74F299N	SN74F299N
0°C to 70°C	COIC DW	Tube of 25		F200
0 0 10 70 0	SOIC - DW	Reel of 2000	SN74F299DWR	F299
	SOP - NS	Reel of 2000	SN74F299NSR	74F299

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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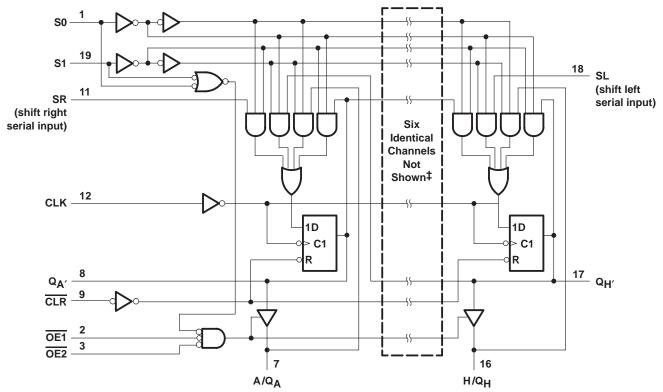
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#### **FUNCTION TABLE**

MODE				INP	UTS				I/O PORTS								OUTPUTS	
MODE	CLR	S1	S0	OE1†	OE2†	CLK	SL	SR	A/Q <sub>A</sub>	B/QB	C/QC	D/QD	E/Q <sub>E</sub>	F/Q <sub>F</sub>	G/Q <sub>G</sub>	H/Q <sub>H</sub>	$Q_{A'}$	$Q_{H'}$
	L	Χ	L	L	L	Χ	Χ	Χ	L	L	L	L	L	L	L	L	L	L
Clear	L	L	Χ	L	L	X	Χ	Χ	L	L	L	L	L	L	L	L	L	L
	L	Н	Н	X	X	Χ	Χ	X	Х	X	X	X	X	X	Χ	X	L	L
Hold	Н	L	L	L	L	Χ	Х	Χ	Q <sub>A0</sub>	Q <sub>B0</sub>	Q <sub>C0</sub>	Q <sub>D0</sub>	Q <sub>E0</sub>	Q <sub>F0</sub>	Q <sub>G0</sub>	Q <sub>H0</sub>	Q <sub>A0</sub>	Q <sub>H0</sub>
Поіа	Н	Χ	Χ	L	L	L	Χ	Χ	Q <sub>A0</sub>	$Q_{B0}$	Q <sub>C0</sub>	$Q_{D0}$	Q <sub>E0</sub>	Q <sub>F0</sub>	Q <sub>G0</sub>	Q <sub>H0</sub>	Q <sub>A0</sub>	Q <sub>H0</sub>
Shift	Н	L	Н	L	L	1	Χ	Н	Н	Q <sub>An</sub>	Q <sub>Bn</sub>	QCn	Q <sub>Dn</sub>	Q <sub>En</sub>	Q <sub>Fn</sub>	QGn	Н	QGn
Right	Н	L	Н	L	L	$\uparrow$	Χ	L	L	$Q_{An}$	$Q_{Bn}$	QCn	$Q_{Dn}$	$Q_{En}$	$Q_{Fn}$	QGn	L	QGn
Shift	Н	Н	L	L	L	1	Н	Χ	Q <sub>Bn</sub>	QCn	Q <sub>Dn</sub>	Q <sub>En</sub>	Q <sub>Fn</sub>	QGn	Q <sub>Hn</sub>	Н	Q <sub>Bn</sub>	Н
Left	Н	Н	L	L	L	1	L	Χ	Q <sub>Bn</sub>	QCn	$Q_{Dn}$	Q <sub>En</sub>	Q <sub>Fn</sub>	$Q_{Gn}$	Q <sub>Hn</sub>	L	$Q_{Bn}$	L
Load	Н	Н	Н	Χ	Χ	1	X	Χ	а	b	С	d	е	f	g	h	а	h

NOTE: a . . . h = the level of the steady-state input at inputs A through H, respectively. This data is loaded into the flip-flops while the flip-flop outputs are isolated from the I/O terminals.

## logic diagram (positive logic)



‡ I/O ports not shown: B/QB (13), C/QC (6), D/QD (14), E/QE (5), F/QF (15), and G/QG (4).

<sup>†</sup> When one or both output-enable inputs are high, the eight I/O terminals are disabled to the high-impedance state; however, sequential operation or clearing of the register is not affected.

## SN54F299, SN74F299 8-BIT UNIVERSAL SHIFT/STORAGE REGISTERS WITH 3-STATE OUTPUTS

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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	–0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	
Input current range	–30 mA to 5 mA
Voltage range applied to any output in the disabled or power-off state .	
Voltage range applied to any output in the high state	0.5 V to V <sub>CC</sub>
Current into any output in the low state: Q <sub>A'</sub> or Q <sub>H'</sub>	40 mÅ
SN54F299 (Q <sub>A</sub> thru Q <sub>H</sub> )	40 mA
SN74F299 (Q <sub>A</sub> thru Q <sub>H</sub> )	48 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): DW package	58°C/W
N package	69°C/W
NS package	60°C/W
Storage temperature range, T <sub>stg</sub>	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input voltage ratings may be exceeded provided the input current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

## recommended operating conditions (see Note 3)

			S	N54F29	9	SN74F299			
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
$V_{IH}$	High-level input voltage		2			2			V
$V_{IL}$	Low-level input voltage				0.8			0.8	V
lıK	Input clamp current				-18			-18	mA
	IPak lavel extend someof	Q <sub>A</sub> ' or Q <sub>H</sub> '			- 1			- 1	4
ЮН	High-level output current	Q <sub>A</sub> thru Q <sub>H</sub>			-3			-3	mA
		Q <sub>A</sub> ' or Q <sub>H</sub> '			20			20	
lOL	Low-level output current	Q <sub>A</sub> thru Q <sub>H</sub>			20			24	mA
TA	Operating free-air temperature		-55		125	0		70	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				S	N54F29	9	S	N74F299	)	LINUT
PA	ARAMETER	TES	r conditions	MIN	TYP†	MAX	MIN	TYP	MAX	UNIT
VIK		$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V
	Q <sub>A</sub> ' or Q <sub>H</sub> '		I <sub>OH</sub> = – 1 mA	2.5	3.4		2.5	3.4		
\/ - · ·	O . them. O .	V <sub>CC</sub> = 4.5 V	$I_{OH} = -1 \text{ mA}$	2.5	3.4		2.5	3.4		V
VOH	Q <sub>A</sub> thru Q <sub>H</sub>		IOH = -3  mA	2.4	3.3		2.4	3.3		V
	Any output	$V_{CC} = 4.75 \text{ V},$	$I_{OH} = -1 \text{ mA to } -3 \text{ mA}$				2.7			
	$Q_{A'}$ or $Q_{H'}$		$I_{OL} = 20 \text{ mA}$		0.3	0.5		0.3	0.5	
VOL	0 11	V <sub>CC</sub> = 4.5 V	$I_{OL} = 20 \text{ mA}$		0.3	0.5				V
Q <sub>A</sub> thru Q <sub>H</sub>		$I_{OL} = 24 \text{ mA}$					0.35	0.5		
	A thru H	V 55V	V <sub>I</sub> = 5.5 V			1			1	4
1 <sub>1</sub>	Any other	$V_{CC} = 5.5 \text{ V}$	V <sub>I</sub> = 7 V			0.1			0.1	mA
. +	A thru H	V 55V	V 07V			70			70	•
¹ <sub>IH</sub> ‡	Any other	$V_{CC} = 5.5 \text{ V},$	$V_{I} = 2.7 \text{ V}$			20			20	μΑ
	A thru H					-0.65			-0.65	
I <sub>IL</sub> ‡	S0 or S1	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 0.5 V			-1.2			-1.2	mA
	Any other					-0.6			-0.6	
IOS§		V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 0	-60		-150	-60		-150	mA
Icc		V <sub>CC</sub> = 5.5 V,	See Note 4		68	95		68	95	mA

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

NOTE 4: ICC is measured with  $\overline{\text{OE1}}$ ,  $\overline{\text{OE2}}$ , and CLK at 4.5 V.

## timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

				V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C SN54		SN54	SN54F299 SN74F299		F299	UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency				70		65		70	MHz
	Dulan donation	CLK high or low		7		8		7		
t <sub>W</sub>	Pulse duration	CLR low	7		8		7		ns	
	Setup time before	S0 or S1	High or low	8.5		9.5		8.5		
t	CLK↑	A/Q <sub>A</sub> thru H/Q <sub>H</sub> , SR, or SL	High or low	5.5		6.5		5.5		ns
t <sub>su</sub>	Inactive-state setup time before CLK↑¶	CLR	High	7		13		7		113
	Hald time after CLICT	S0 or S1	High or low	0		0		0		
<sup>t</sup> h	n Hold time after CLK↑	A/Q <sub>A</sub> thru H/Q <sub>H</sub> , SR, or SL	High or low	2	·	2	·	2		ns

<sup>¶</sup> Inactive-state setup time also is referred to as recovery time.



<sup>‡</sup> For I/O ports (QA thru QH), the parameters I<sub>IH</sub> and I<sub>IL</sub> include the off-state output current.

<sup>§</sup> Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

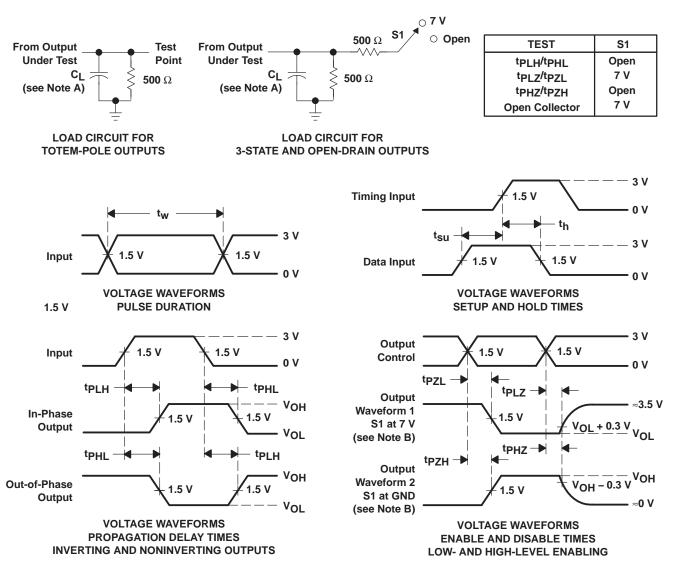
## switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5 \text{ V},$ $C_{L} = 50 \text{ pF},$ $R_{L} = 500 \Omega,$ $T_{A} = 25^{\circ}\text{C}$			V <sub>C</sub> C <sub>L</sub> R <sub>L</sub> T <sub>A</sub>	UNIT			
			MIN	TYP	MAX	MIN	MAX	SN74	MAX	
f <sub>max</sub>			70	100		65		70		MHz
t <sub>PLH</sub>	0114		3.2	6.6	9	2.7	10.5	3.2	10	
tPHL	CLK	Q <sub>A</sub> ′ or Q <sub>H</sub> ′	2.7	6.1	8.5	2.2	10	2.7	9.5	ns
t <sub>PLH</sub>	OLIV	O 4h O	3.2	6.6	9	2.7	11	3.2	10	
t <sub>PHL</sub>	CLK	Q <sub>A</sub> thru Q <sub>H</sub>	4.2	8.1	11	3.7	12.5	4.2	12	ns
		Q <sub>A′</sub> or Q <sub>H′</sub>	3.7	7.1	9.5	3.2	11.5	3.7	10.5	
<sup>t</sup> PHL	CLR	Q <sub>A</sub> thru Q <sub>H</sub>	5.7	10.6	14	5	15.5	5.7	15	ns
t <sub>PZH</sub>	054 050	0 4 0	2.7	5.6	8	2.2	10.5	2.7	9	
tPZL	OE1 or OE2	Q <sub>A</sub> thru Q <sub>H</sub>	3.2	6.6	10	2.7	12	3.2	11	ns
t <sub>PHZ</sub>	OE1 or OE2	0.11.0		4.1	6	1.7	9	1.7	7	200
t <sub>PLZ</sub>	OET OF OE2	Q <sub>A</sub> thru Q <sub>H</sub>	1.2	3.6	5.5	1.2	7.5	1.2	6.5	ns

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

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#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq 2.5$  ns,  $t_f \leq 2.5$  ns, duty cycle = 50%.
- D. The outputs are measured one at a time, with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

www.ti.com 11-Nov-2025

#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
SN74F299DW	Obsolete	Production	SOIC (DW)   20	-	-	Call TI	Call TI	0 to 70	F299
SN74F299DWR	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	F299
SN74F299DWR.A	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	F299
SN74F299N	Active	Production	PDIP (N)   20	20   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74F299N
SN74F299N.A	Active	Production	PDIP (N)   20	20   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74F299N
SN74F299NS.A	Active	Production	SOP (NS)   20	40   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74F299

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.



# **PACKAGE OPTION ADDENDUM**

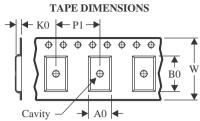
www.ti.com 11-Nov-2025

# **PACKAGE MATERIALS INFORMATION**

www.ti.com 24-Jul-2025

### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	_	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74F299DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

# **PACKAGE MATERIALS INFORMATION**

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#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74F299DWR	SOIC	DW	20	2000	356.0	356.0	45.0

# **PACKAGE MATERIALS INFORMATION**

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### **TUBE**



\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74F299N	N	PDIP	20	20	506	13.97	11230	4.32
SN74F299N.A	N	PDIP	20	20	506	13.97	11230	4.32
SN74F299NS.A	NS	SOP	20	40	530	10.5	4000	4.1

## **MECHANICAL DATA**

# NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



# N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



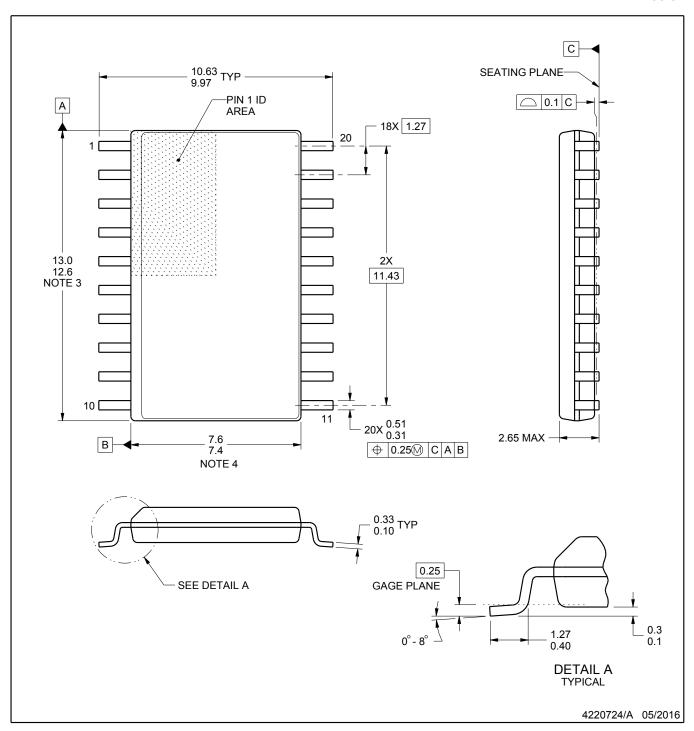
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOIC



#### NOTES:

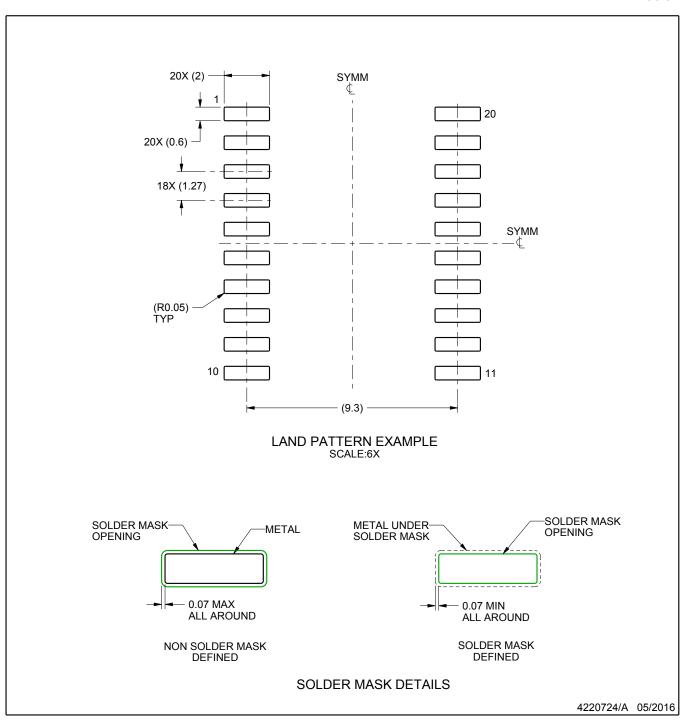
- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



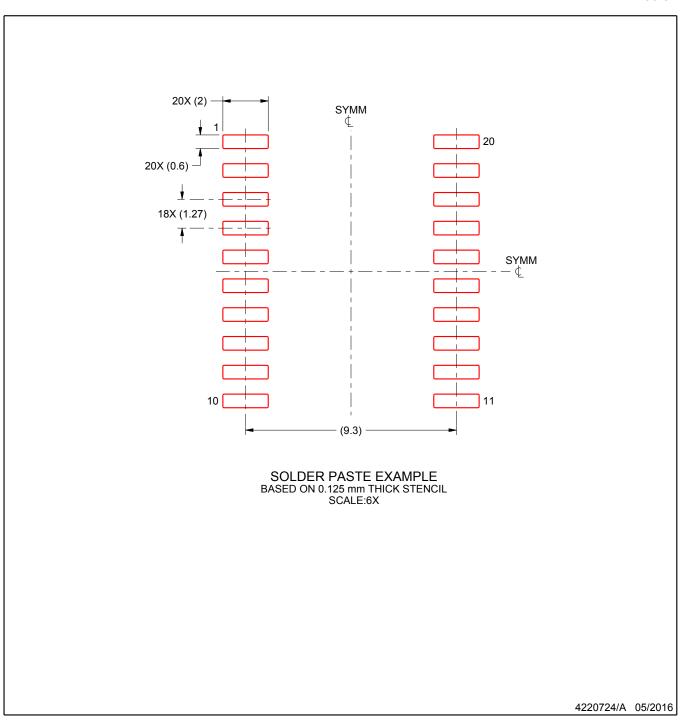
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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